

Patent Application No. 10/690,113

IN THE CLAIMS:

Please amend claims 1, 17, 18, 28 and 30 as follows:

Claim 1. (currently amended) A trace cover suitable for shielding a conductive trace on a circuit board, the circuit board includes at least one circuit ground, the trace cover comprising:

5 a body composed of a dielectric substrate, the body having a top surface, a bottom surface and side surfaces, the bottom surface of the body configured to be disposed substantially over the conductive trace; and

10 top shielding disposed on the top surface of the body, the top shielding configured to be electrically coupled with the at least one circuit ground of the circuit board; and

wherein the trace cover is configured to be fixed to an at least partially exposed circuit board surface.

Claim 2. (previously presented) The trace cover of claim 1, further comprising side shielding perpendicular to the direction of the conductive trace and substantially parallel to the length of the conductive trace, the side shielding configured to be electrically  
5 coupled with the at least one circuit ground of the circuit board.

Claim 3. (previously presented) The trace cover of claim 2, further comprising at least one connecting pad disposed on the bottom surface of the body, the connecting pad configured to be soldered to a top surface of the circuit board and to electrically couple the side  
5 shielding with the at least one circuit ground.

Claim 4. (original) The trace cover of claim 2, wherein the side shielding includes a plurality of conductive vias disposed between the top surface and bottom surface of the body.

Claim 5. (original) The trace cover of claim 4, wherein the plurality of conductive vias are spaced approximately one-quarter inch apart.

Claim 6. (original) The trace cover of claim 2, wherein the side shielding includes a conductive plating disposed along the side surfaces of the body.

Application Serial No: 10/143,149

Claim 7. (original) The trace cover of claim 1, wherein the top shielding is a conductive plating.

Claim 8. (original) The trace cover of claim 1, wherein the top shielding is electrically coupled to the circuit ground through the side shielding.

Claim 9. (original) The trace cover of claim 1, wherein the dielectric substrate of the body is different than a dielectric substrate of the circuit board.

Claims 10-16 (canceled)

Claim 17. (currently amended) A circuit board comprising:  
a conductive trace disposed on an outer surface of the circuit board;

5 a plurality of circuit components disposed on the outer surface  
of the circuit board; and  
means for shielding the conductive trace, the means for shielding  
disposed on the outer surface of the circuit board.

Claim 18. (currently amended) A trace cover suitable for suppressing electromagnetic emissions from a conductive bus on a circuit board, the conductive bus including at least two substantially parallel bus traces, the circuit board including a partially exposed  
5 circuit board surface and at least one circuit ground, the trace cover comprising:

a body composed of a dielectric substrate, the body having a top surface, a bottom surface and side surfaces, the bottom surface of the body configured to be disposed substantially over the conductive bus  
10 and on the partially exposed circuit board surface;

side shielding perpendicular to the direction of the conductive bus and substantially parallel to the length of the conductive bus, the side shielding being electrically coupled with the at least one circuit ground of the circuit board; and

15 top shielding disposed on the top surface of the body, the top shielding being electrically coupled with the at least one circuit ground of the circuit board.

Patent Application No. 10/690,113

Claim 19. (original) The trace cover of claim 18, further comprising bus shielding disposed within the body and between the bus traces, the bus shielding being electrically coupled with the at least one circuit ground of the circuit board.

Claim 20. (original) The trace cover of claim 19, further comprising at least one connecting pad disposed on the bottom surface of the body, the connecting pad configured to coupled the bus shielding with the at least one circuit ground.

Claim 21. (original) The trace cover of claim 19, wherein the bus shielding includes a plurality of conductive vias disposed between the top surface and bottom surface of the body.

Claim 22. (original) The trace cover of claim 19, wherein the bus shielding is coupled to the circuit ground through the side shielding.

Claim 23. (original) The trace cover of claim 18, wherein the side shielding includes a conductive plating disposed along side surfaces of the body.

Claims 24-26. (canceled)

Claim 27. (previously presented) The trace cover of claim 1, wherein the trace cover is mechanically attached to a top surface of the circuit board after manufacture of the circuit board.

Claim 28. (currently amended) The trace cover of claim 1, wherein the ~~conductive trace is on an outer surface of the circuit board~~ includes a plurality of circuit components mounted thereon.

Claim 29. (previously presented) The trace cover of claim 1, wherein the trace cover is separate from the circuit board and is configured to be attachable to the circuit board during circuit board component attachment.

Claim 30. (currently amended) The trace cover of claim 18, wherein the ~~conductive bus is on an outer surface of the circuit board~~ includes a plurality of circuit components mounted thereon.

Claim 31. (previously presented) The trace cover of claim 18, wherein the trace cover is separate from the circuit board and is

Patent Application No. 10/690,113

configured to be attachable to the circuit board during circuit board component attachment.